

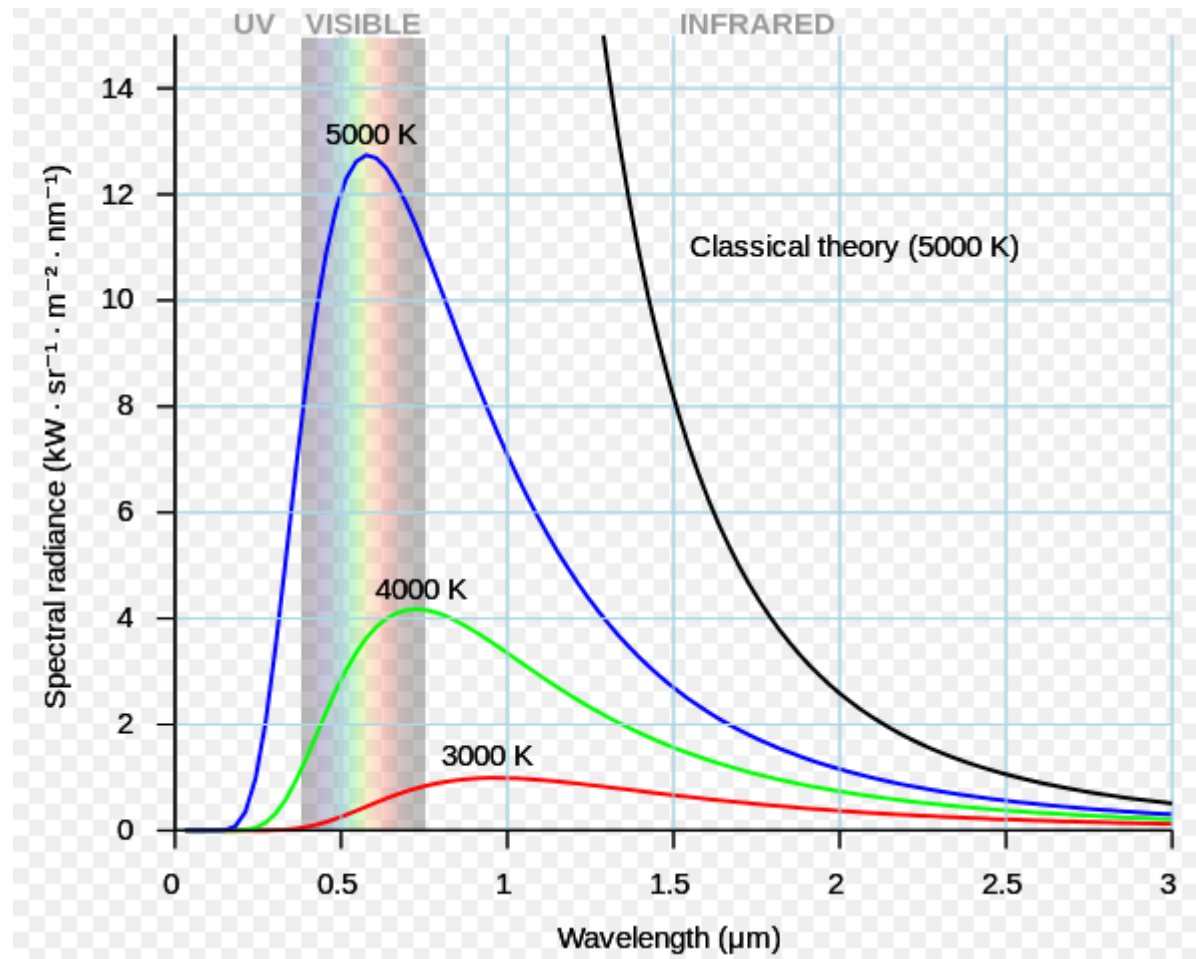
# **From Black-Body Radiation to Next-Generation Electronics**

**C.T. Liu  
2014.11.19**

# Contents:

- 1. From Black-Body Radiation to Transistors**
- 2. Semiconductor Technologies**
- 3. Display Technologies**
- 4. Lighting Technologies**
- 5. 3D Image Systems**
- 6. Conclusion**

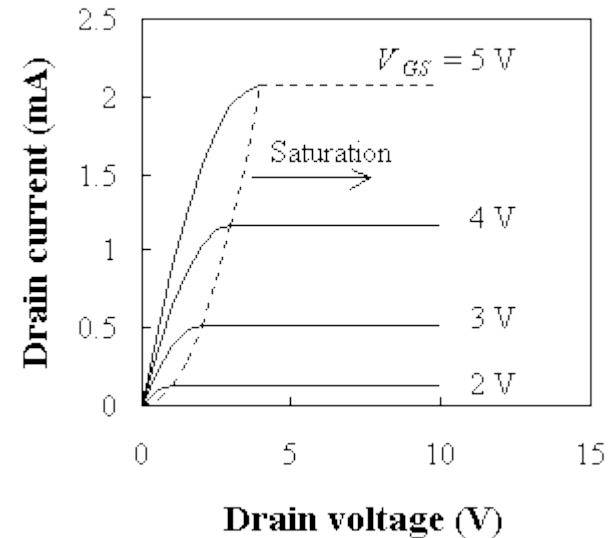
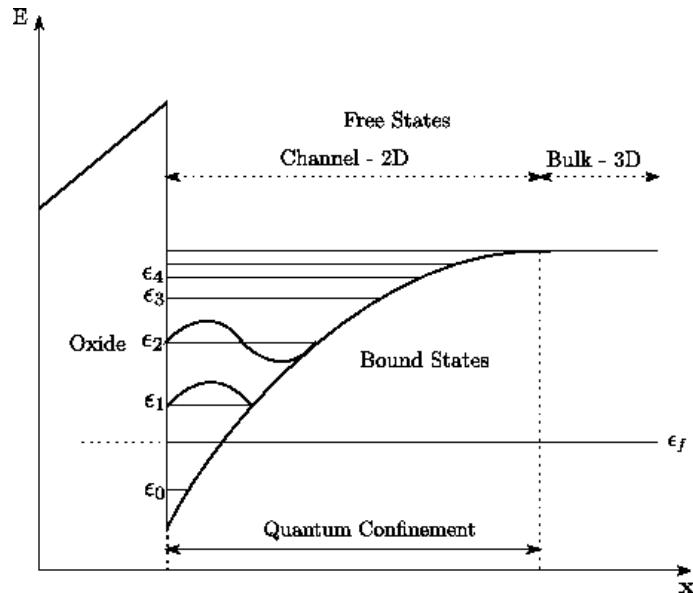
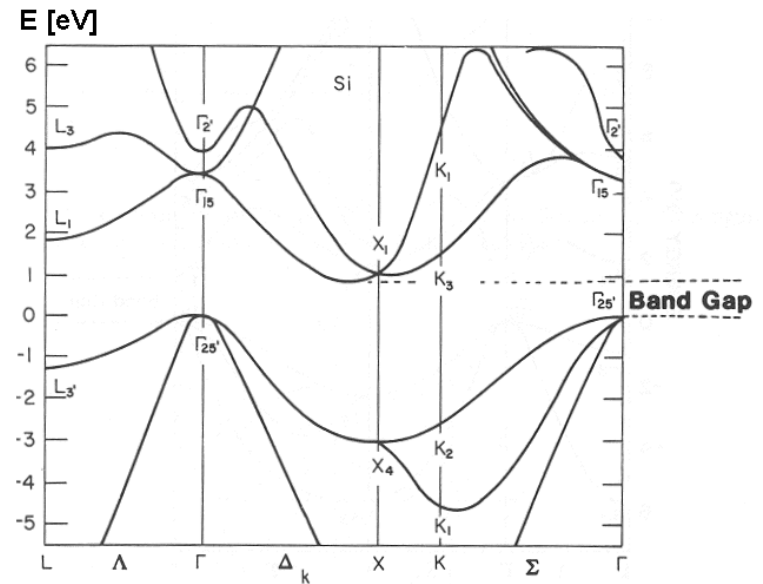
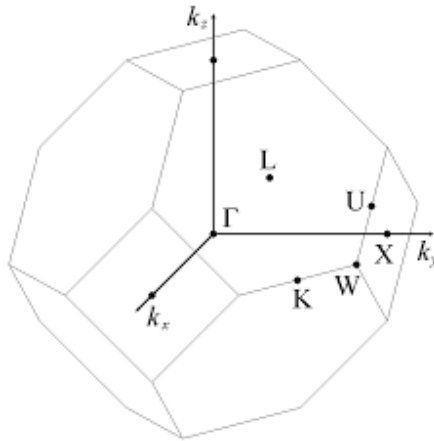
# From Black-Body Radiation to Quantum Mechanics



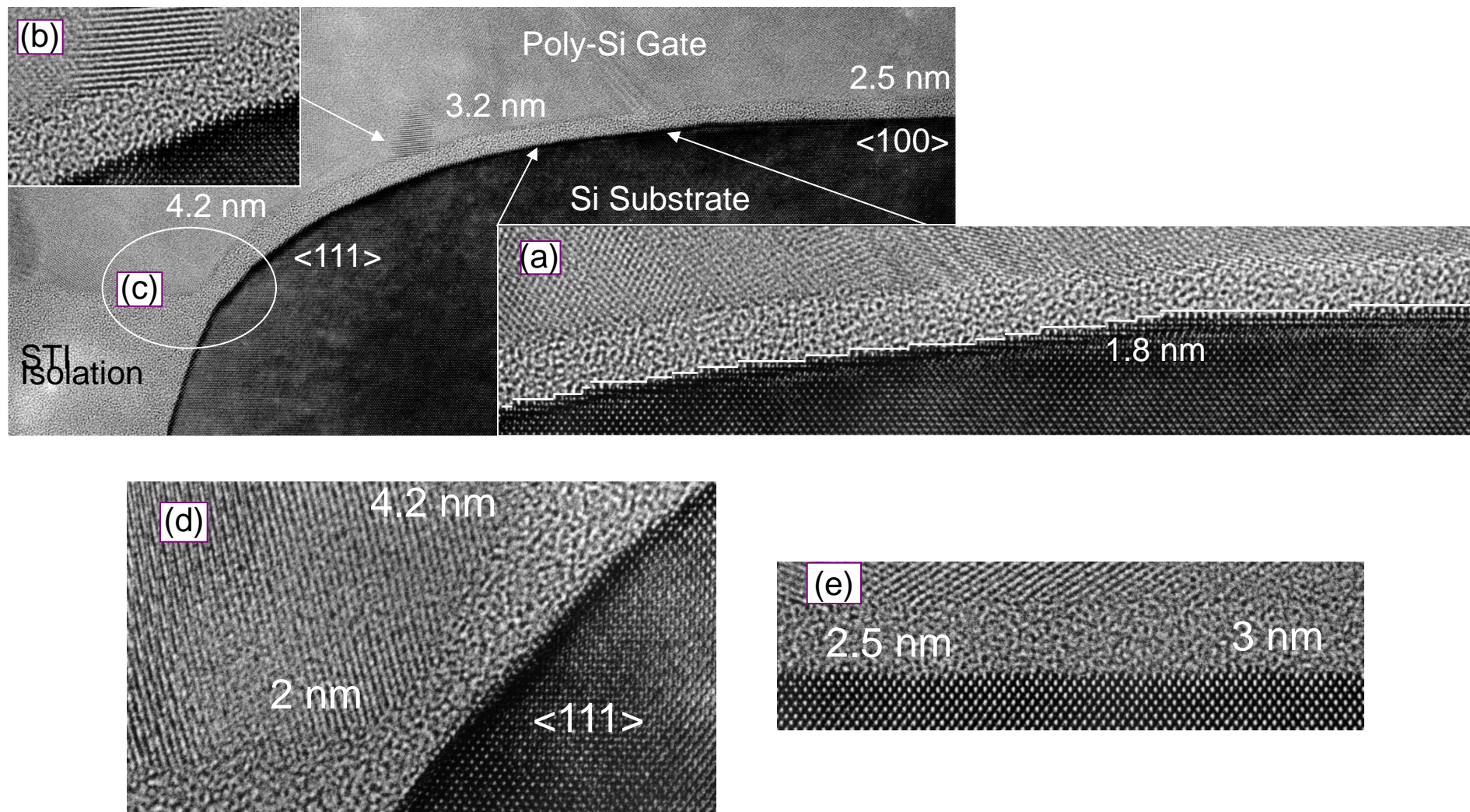
Planck discovered the empirically fitting function, and constructed a physical derivation of this law. In 1901, he expressed  $\epsilon = h \nu$ .  $h$  is now known as [Planck's constant](#).

Ultimately, Planck's law of black-body radiation contributed to Einstein's concept of quanta of light, which became the fundamental basis for the development of [quantum mechanics](#).

# From Quantum Mechanics to Transistors

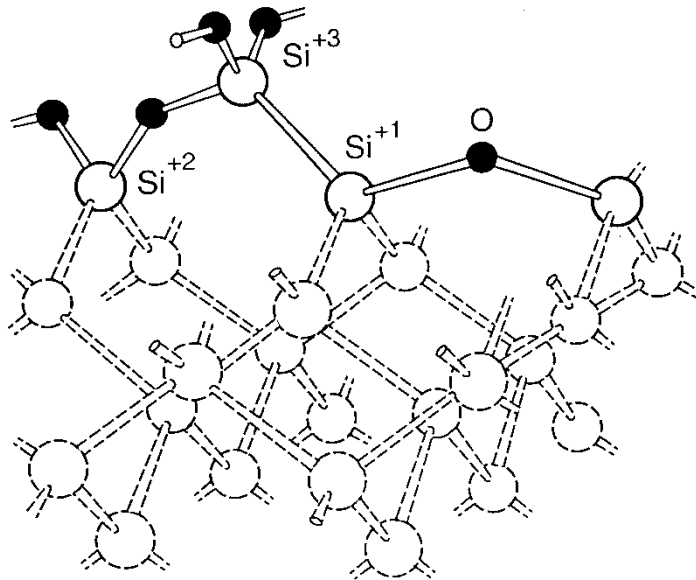


# Thickness Variation

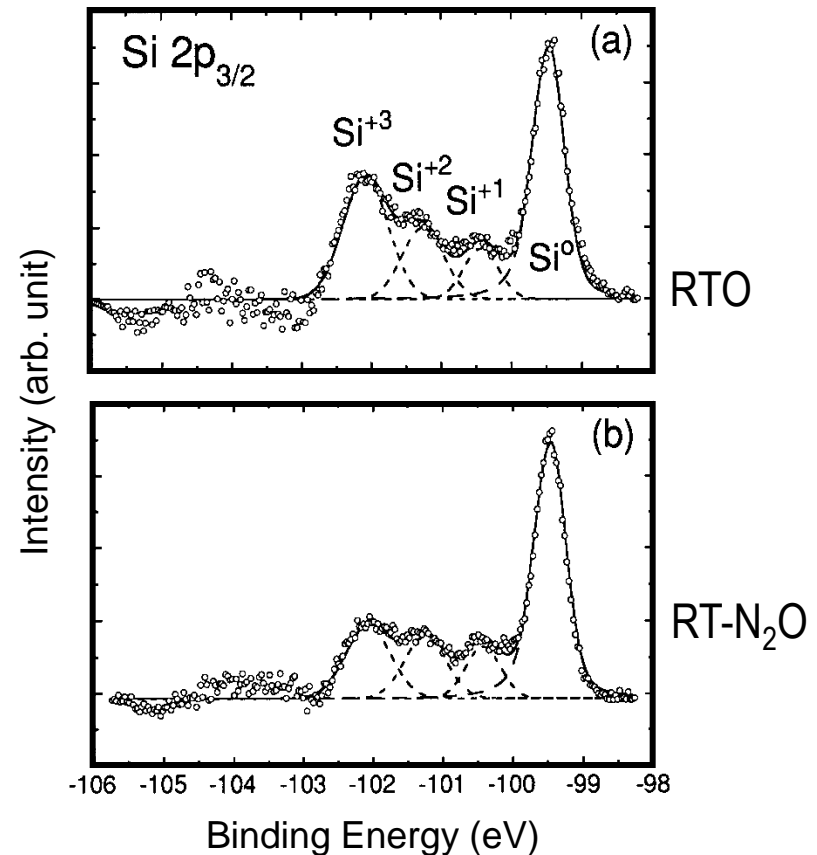


# Sub-Oxide Structures

Interface imperfect bonds can be studied with high-resolution XPS.

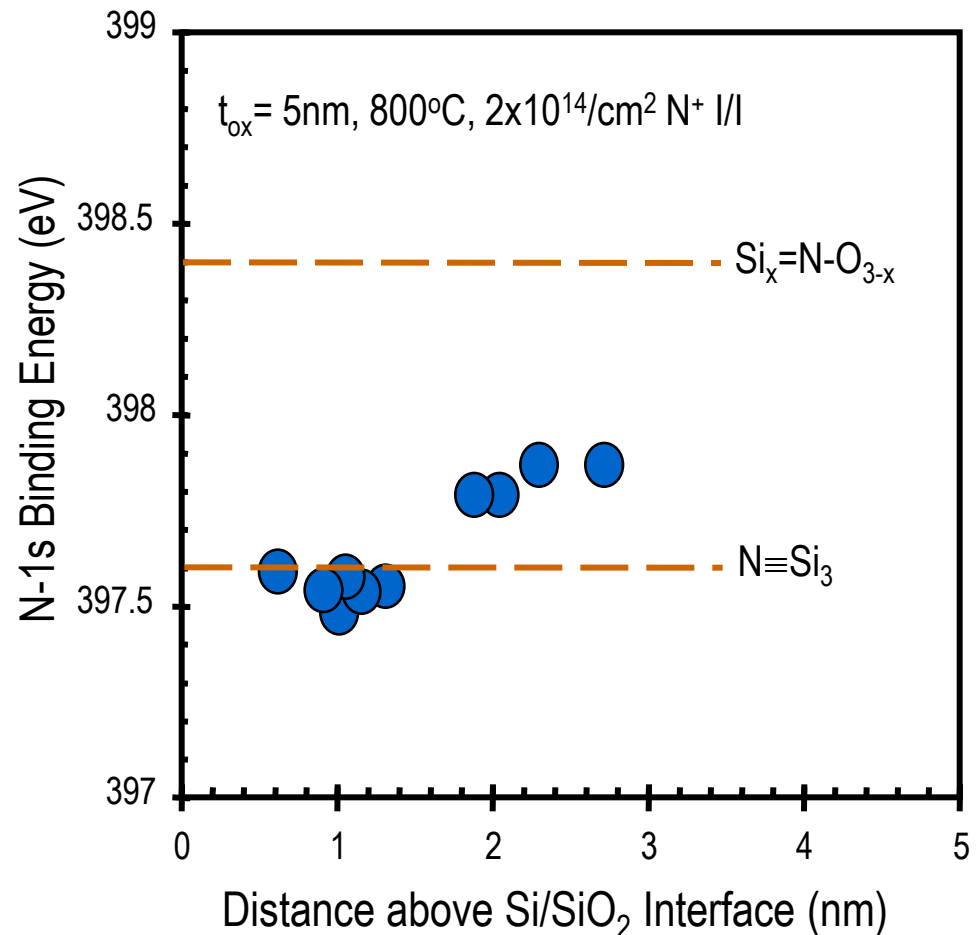


Z.H. Lu, "Synchrotron and Conventional Photoemission Studies of Oxides and N<sub>2</sub>O Oxynitrides," in "Fundamental Aspects of Ultrathin Dielectrics on Si-Based Devices," edited by E. Garfunkel et al., Kluwer Academic Publishers, Netherlands, 1998, p.49.



# Nitrogen Binding Energy

1. N-1s binding energy  $\sim 397.6$  eV, same as  $\text{Si}_3\text{N}_4$ .
2. Longer oxidation increases the binding energy toward 398.4 eV of  $\text{Si}_x\text{=N-O}_{3-x}$ .
3. Wet-oxidation also shifts the binding energy to 398.4 eV.



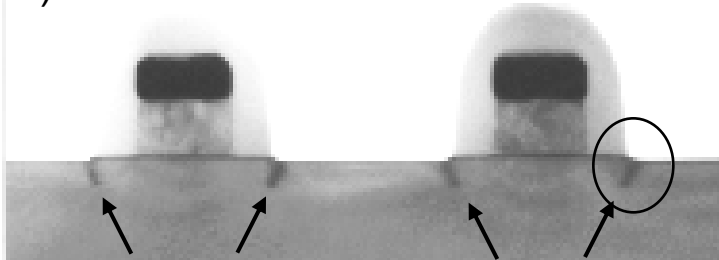


# Substrate Defects

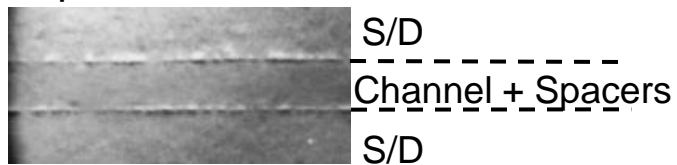
A) After S/D I/I, before RTA



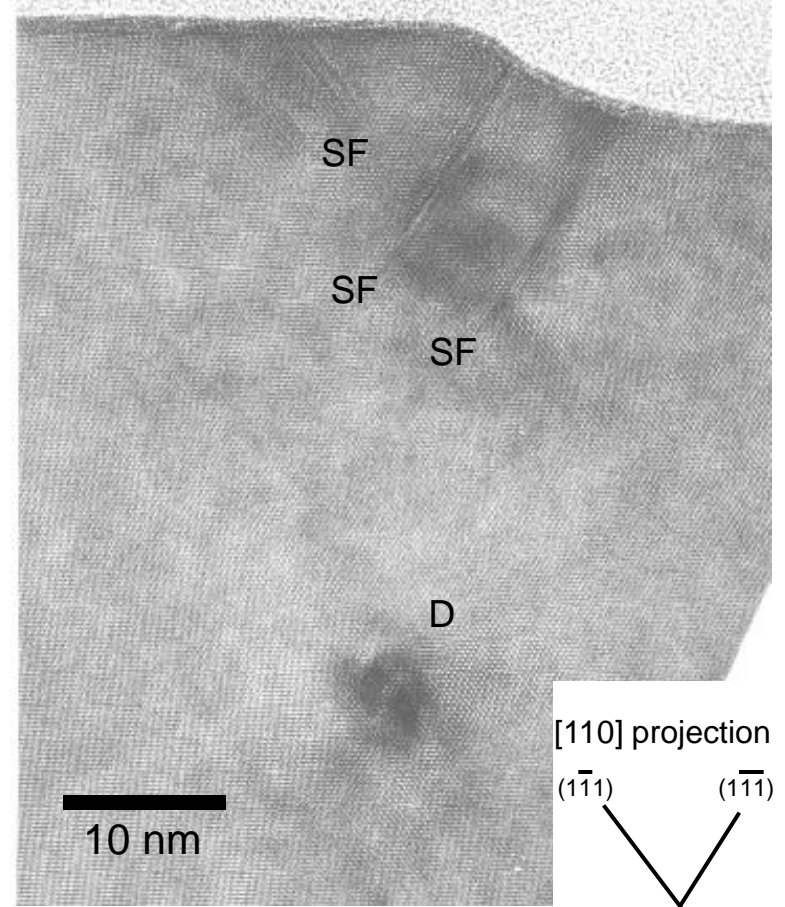
B) After 1050°C 10s RTA



C) Top-Plan View TEM

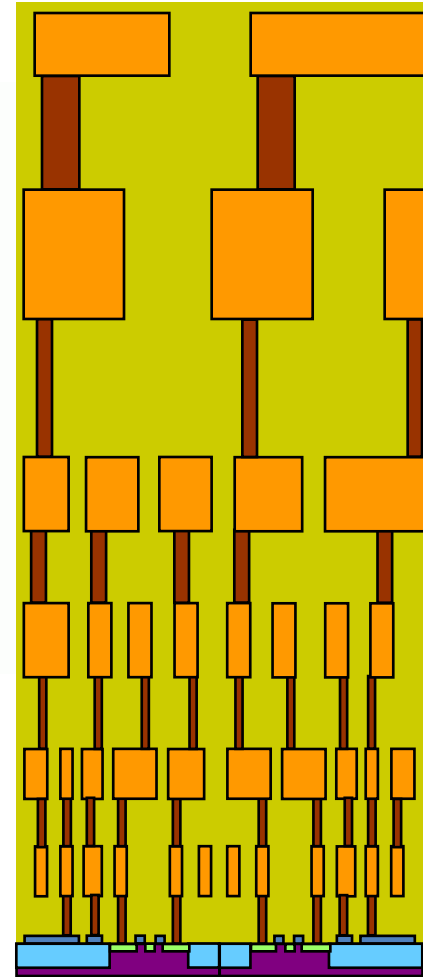
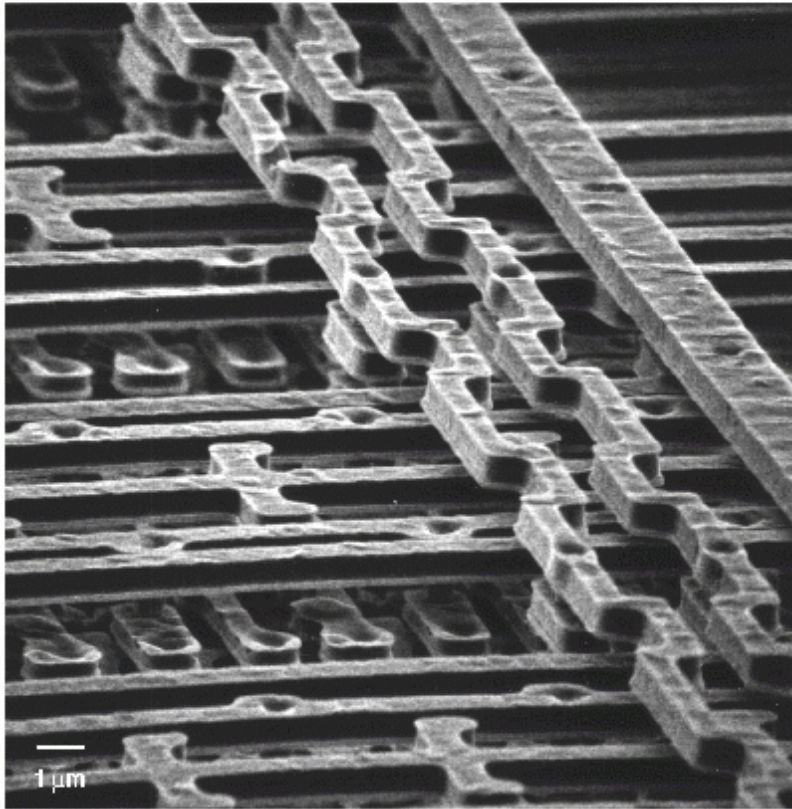


D) XTEM along the channel to S/D

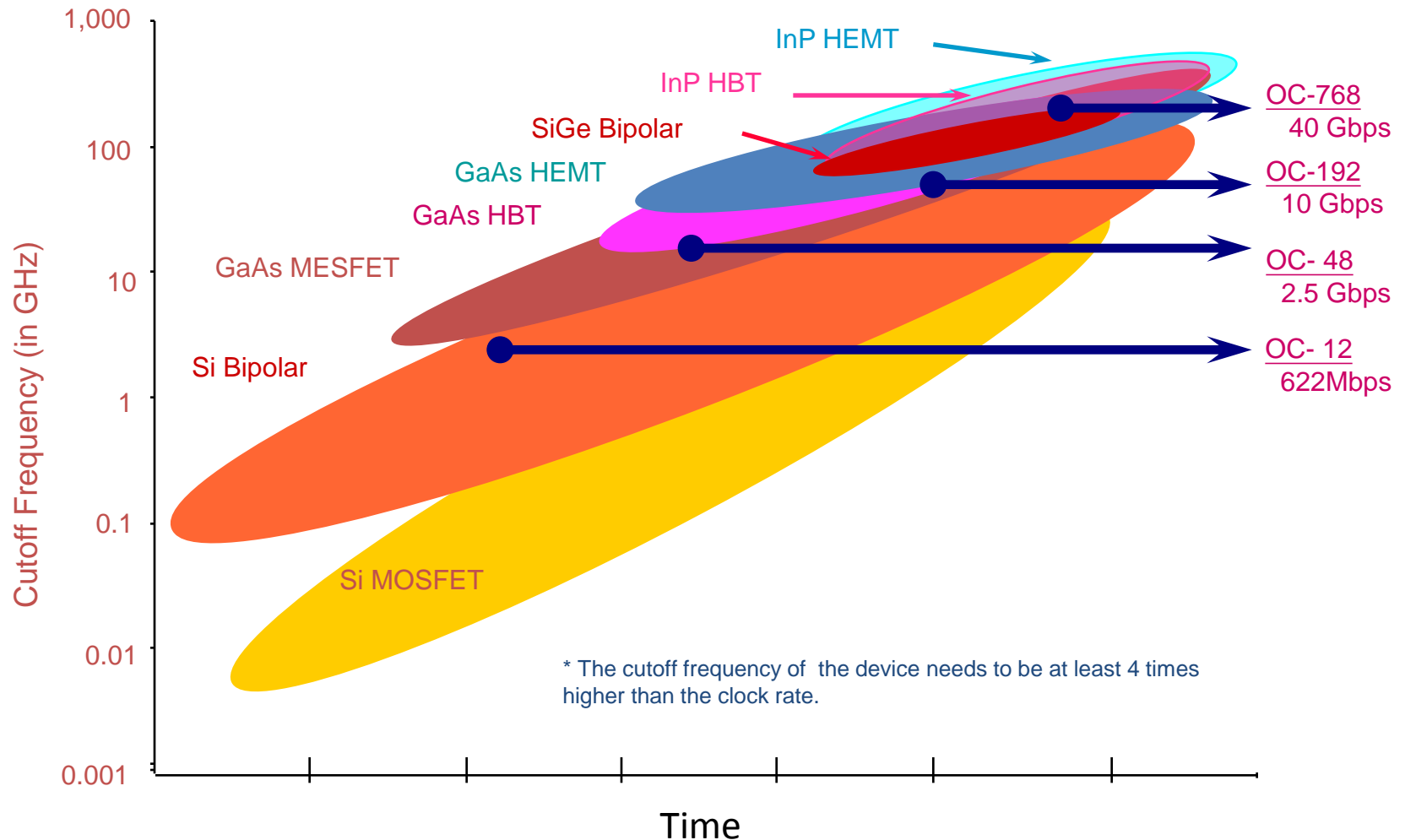




# Interconnect Challenges

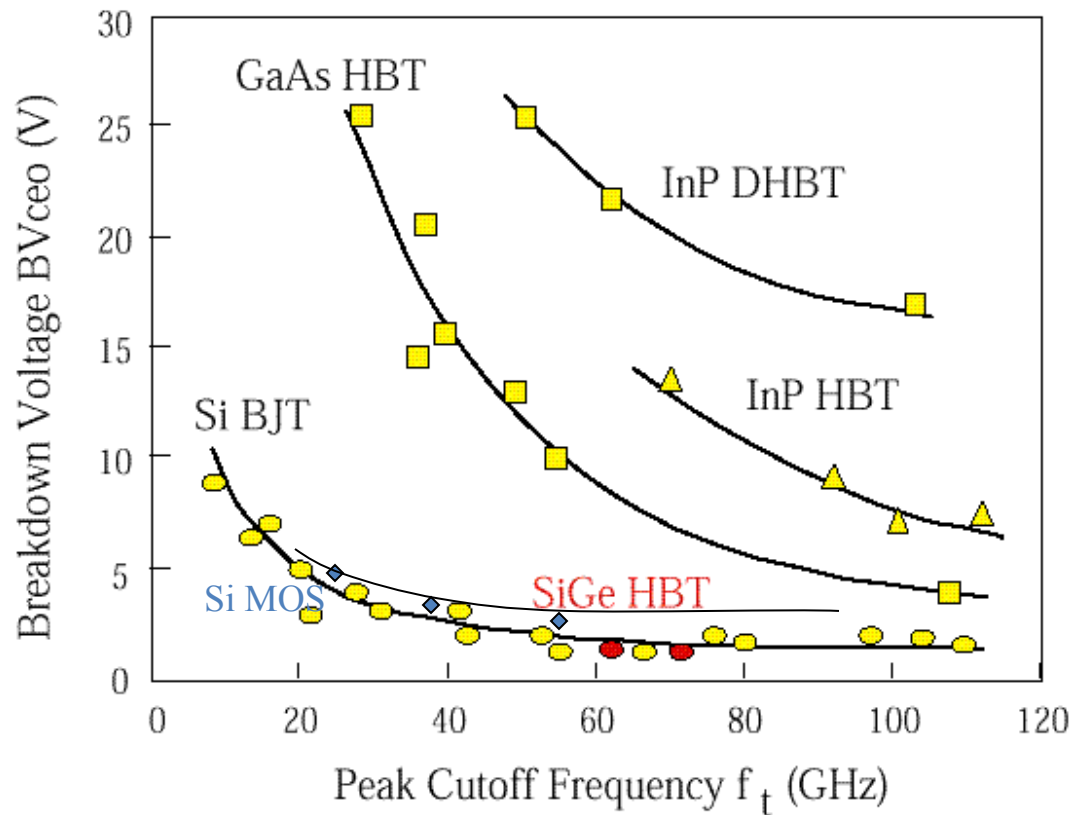


# Communication IC Technology Roadmap



# High-Speed Technologies

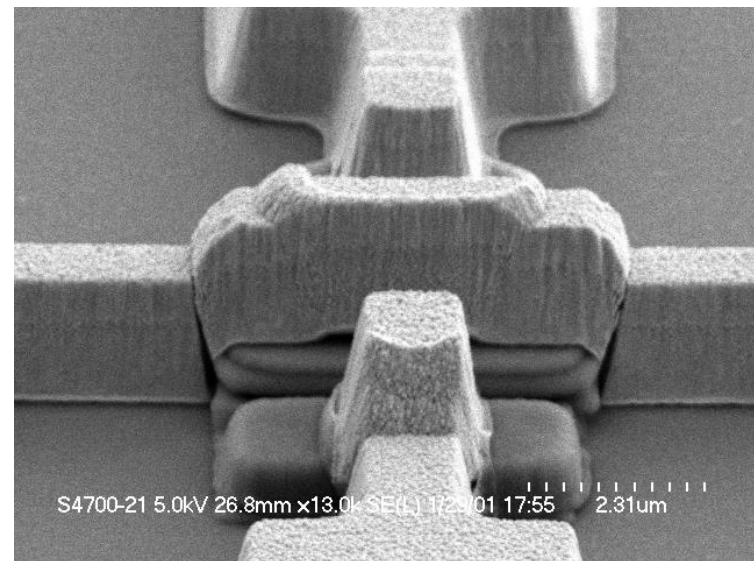
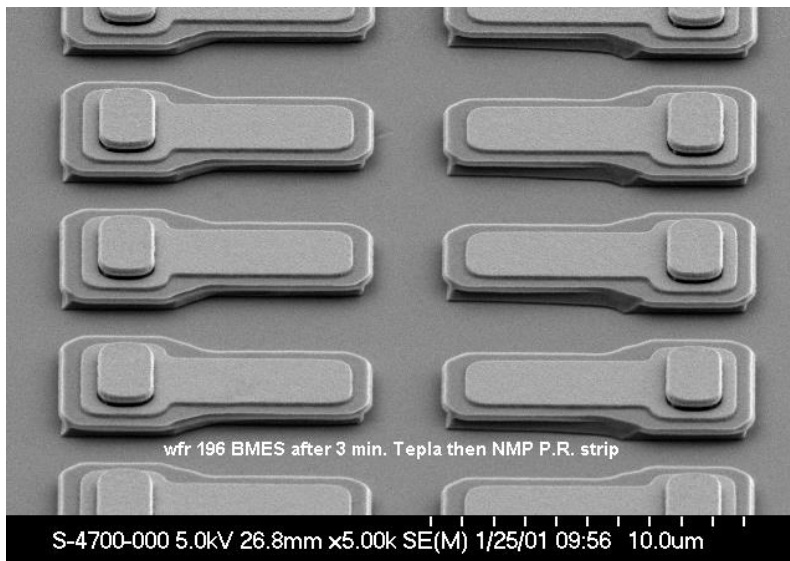
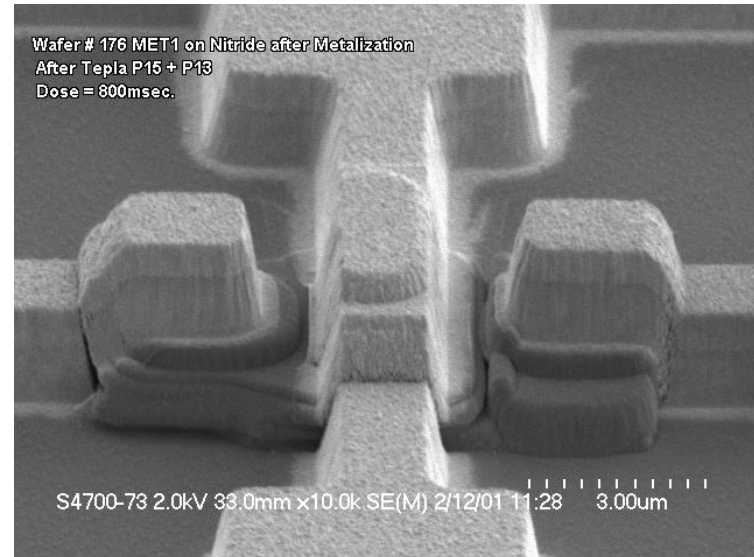
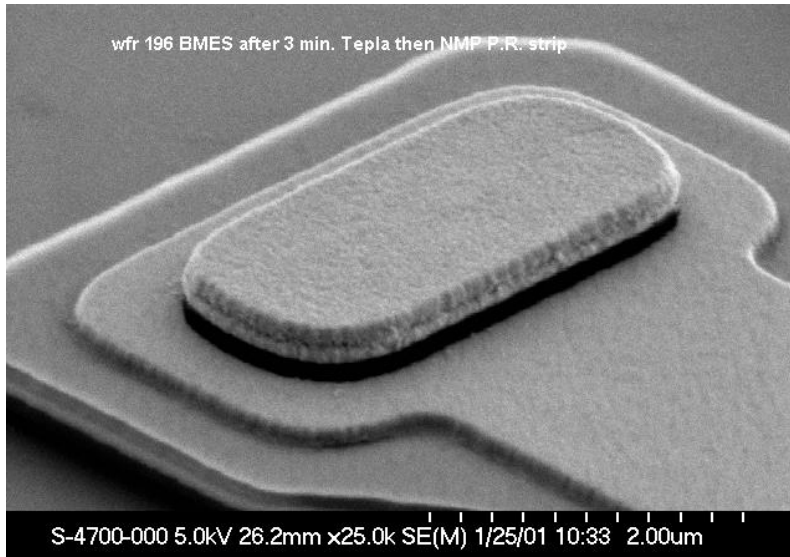
Base-Emitter Breakdown Voltage vs  $f_t$



Parameters for Device Breakdown:

- bandgap energy
- doping density
  - short-channel FETs
- dielectric breakdown
  - short-channel MOS
- space-charge limiting current
  - collector current of BJTs

# InP HBT Device SEMs

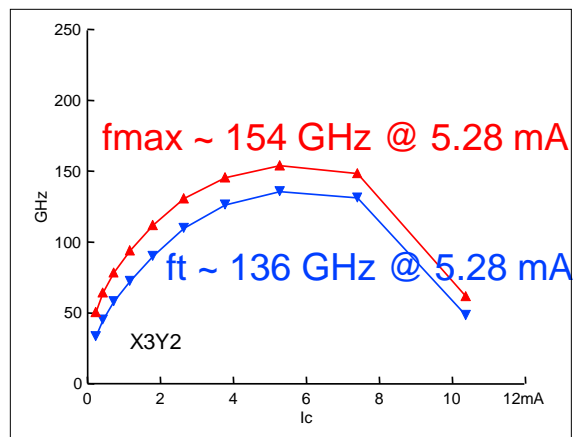
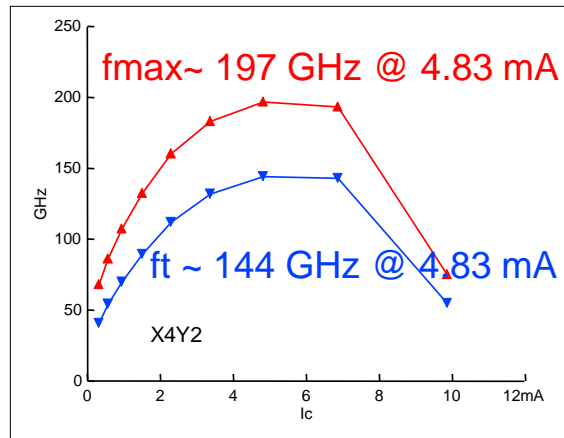


# InP DHBT --- RF Performance

## ft fmax Plot

Lot 51, wafer 203, RF tester 1.6 x 3.4

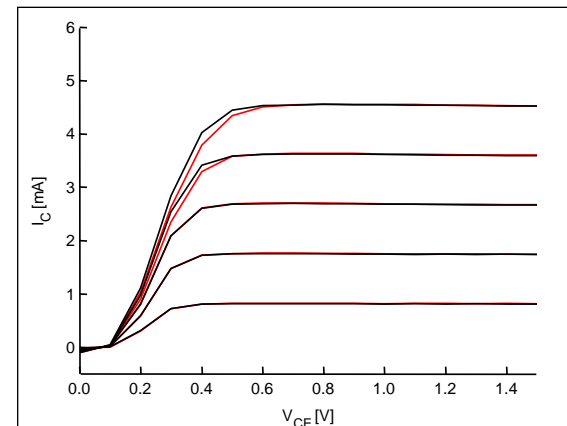
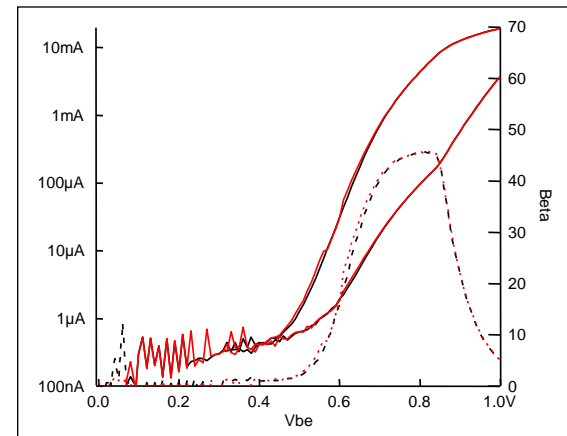
----- ft ----- fmax



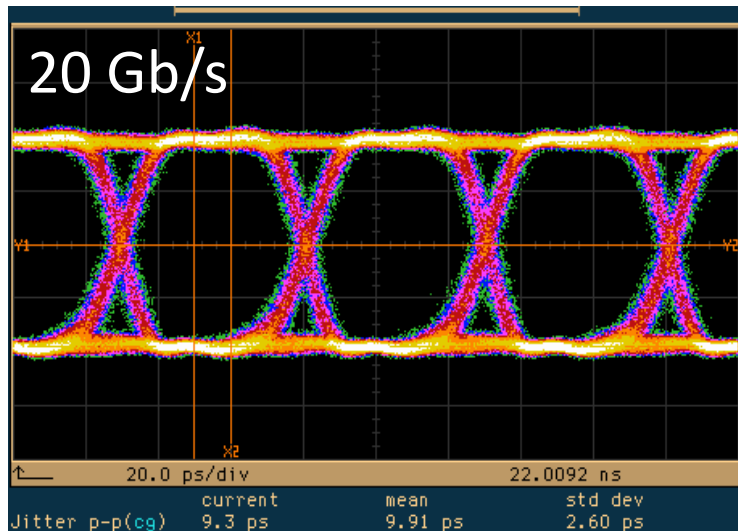
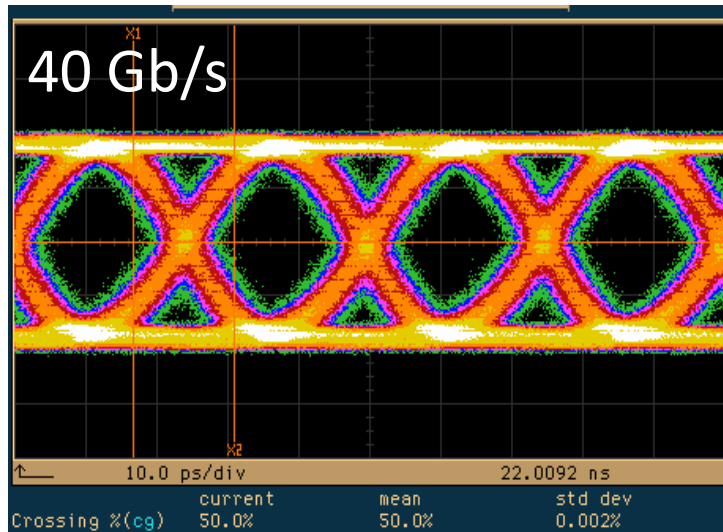
## DC degradation after RF excitation

Lot 51, wafer 203, RF tester 1.6 x 3.4

----- before ----- after



# 40Gb/s Driver Amplifier



Output up to 4.5V (5V simulated)

Bias for this measurement:

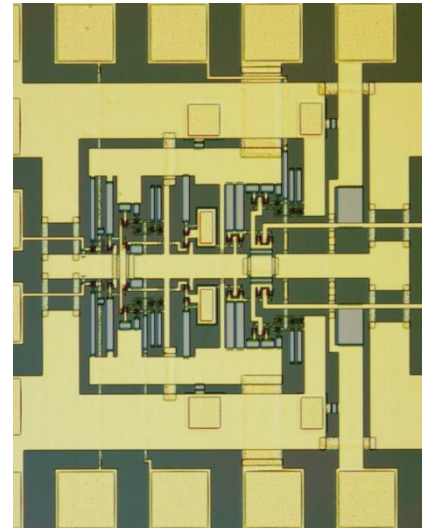
V<sub>ee</sub>=-5.3V, I=190 mA

V<sub>cc1</sub>=0.6V

V<sub>cc2</sub>=2.5V, I=50 mA

Very low power consumption: **1.2 W!!**

- most of jitter caused by 40 Gb/s source
- rise time @ 40Gb/s limited by source, and on-wafer measurement: cables and probes



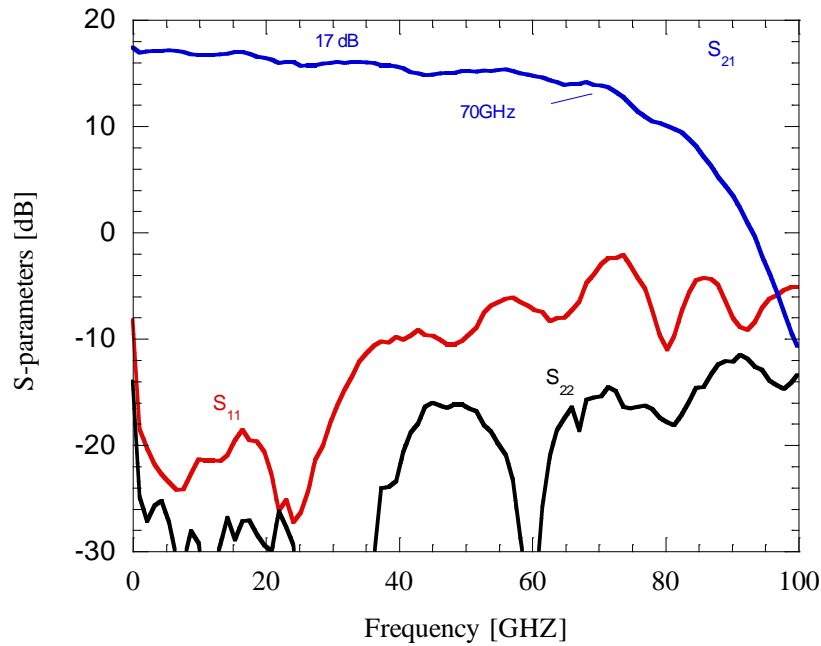
Very compact

circuit size:

**850x850  $\mu\text{m}$**

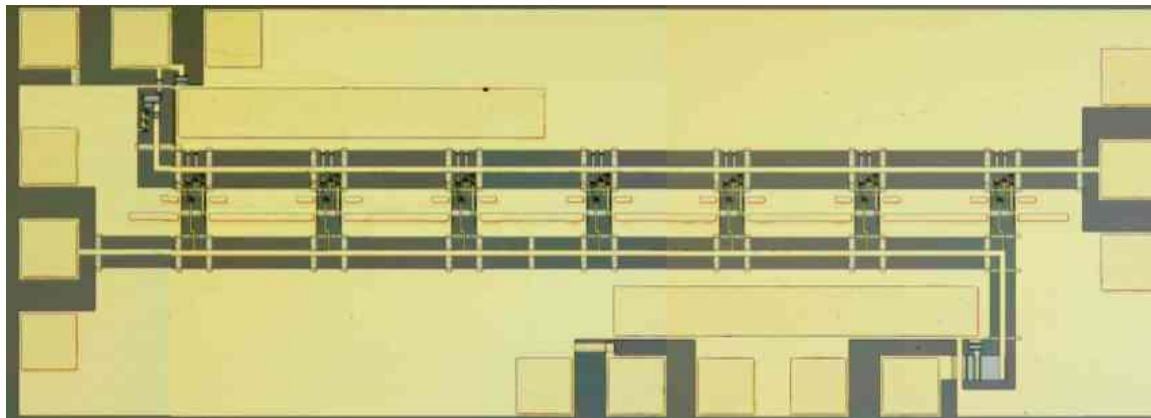


# High Gain-BW Distributed Amplifier for 40Gbps

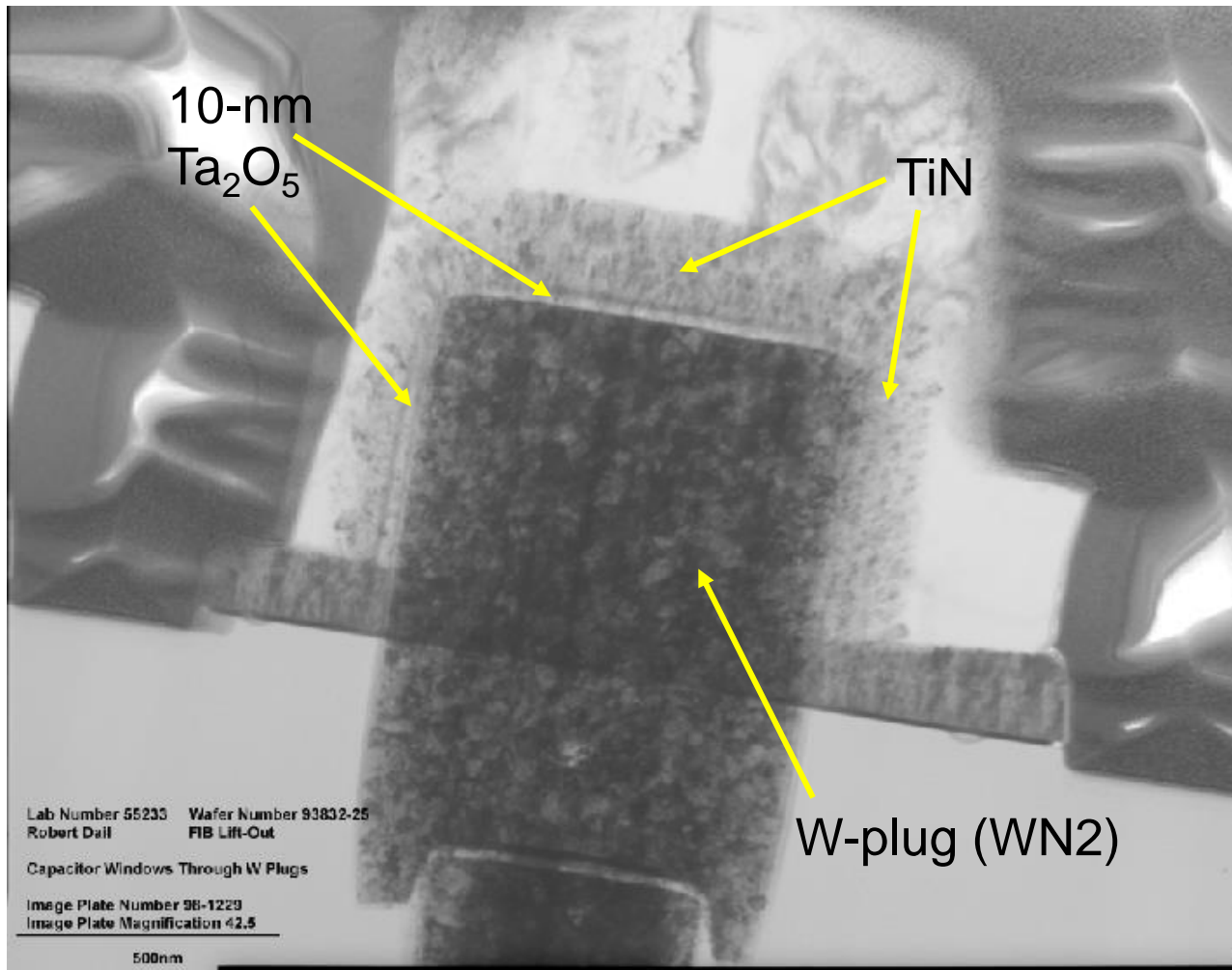


Gain=17 dB  
BW>70 GHz  
GBW>500 GHz  
(record GBW for single-stage DA)

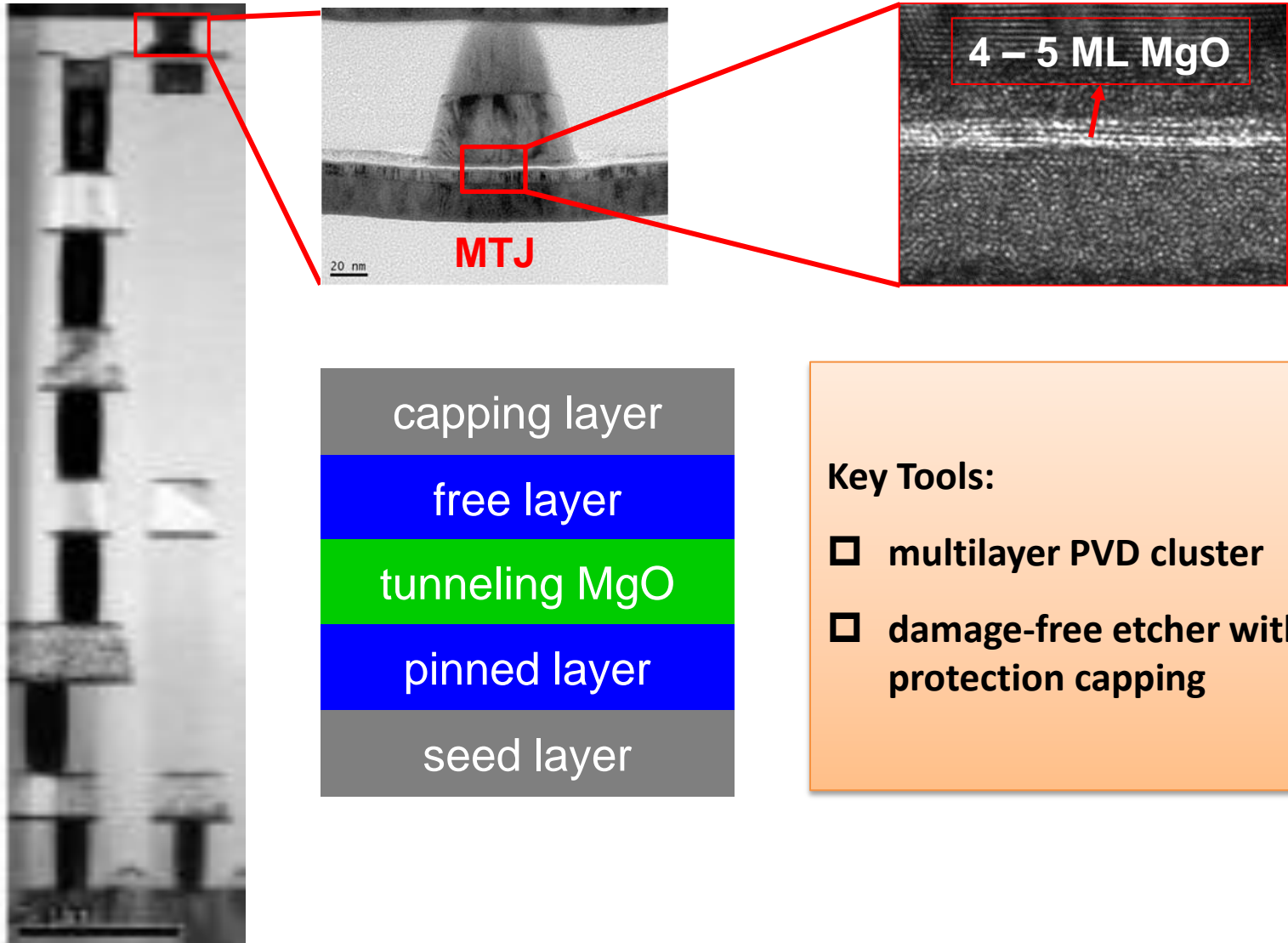
Size:0.7x2mm



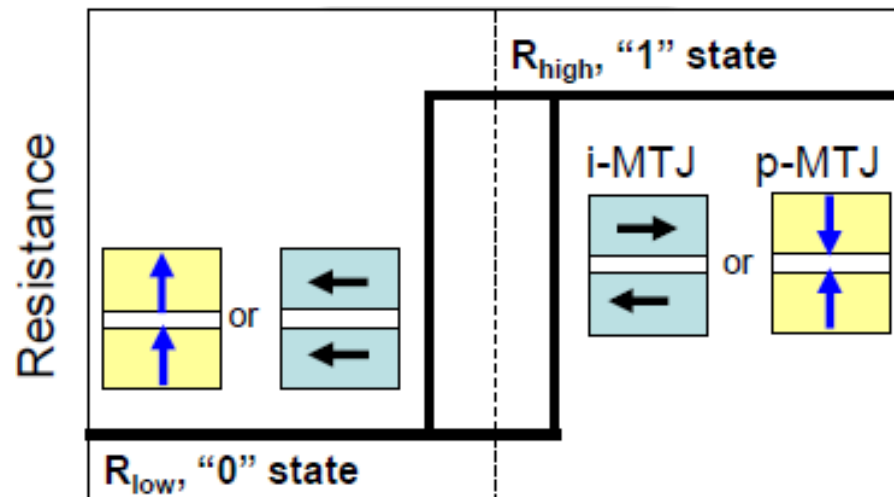
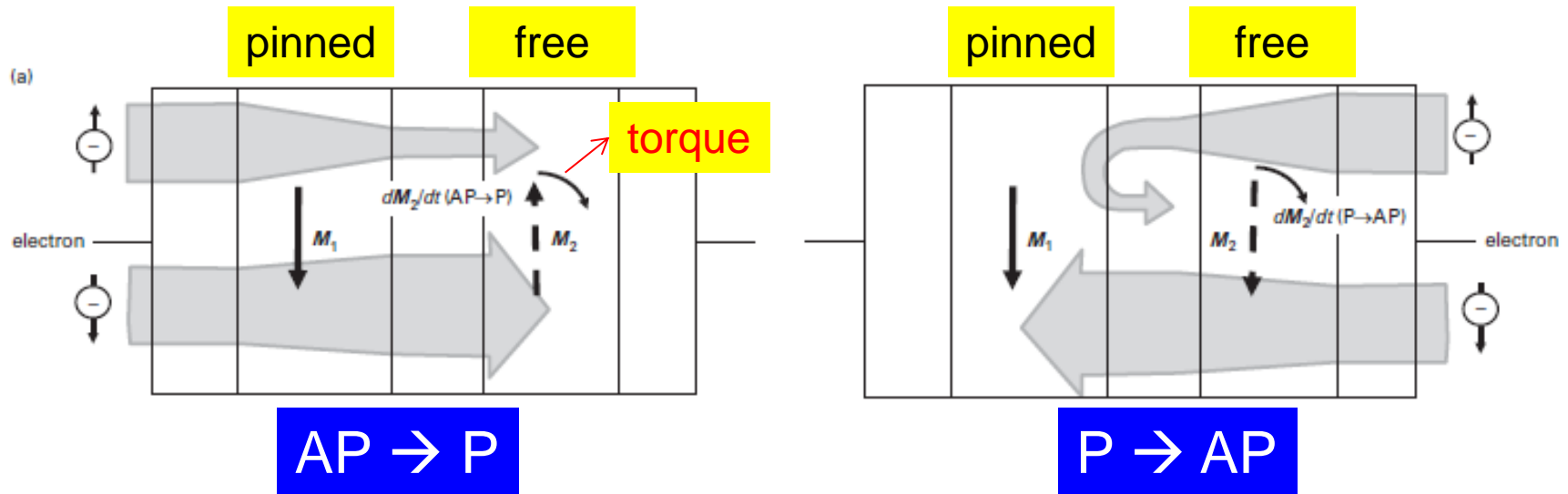
# Metal Ta<sub>2</sub>O<sub>5</sub> MIM Capacitor



# *MRAM: Spintronics*



# Spin-Torque Transfer (STT)



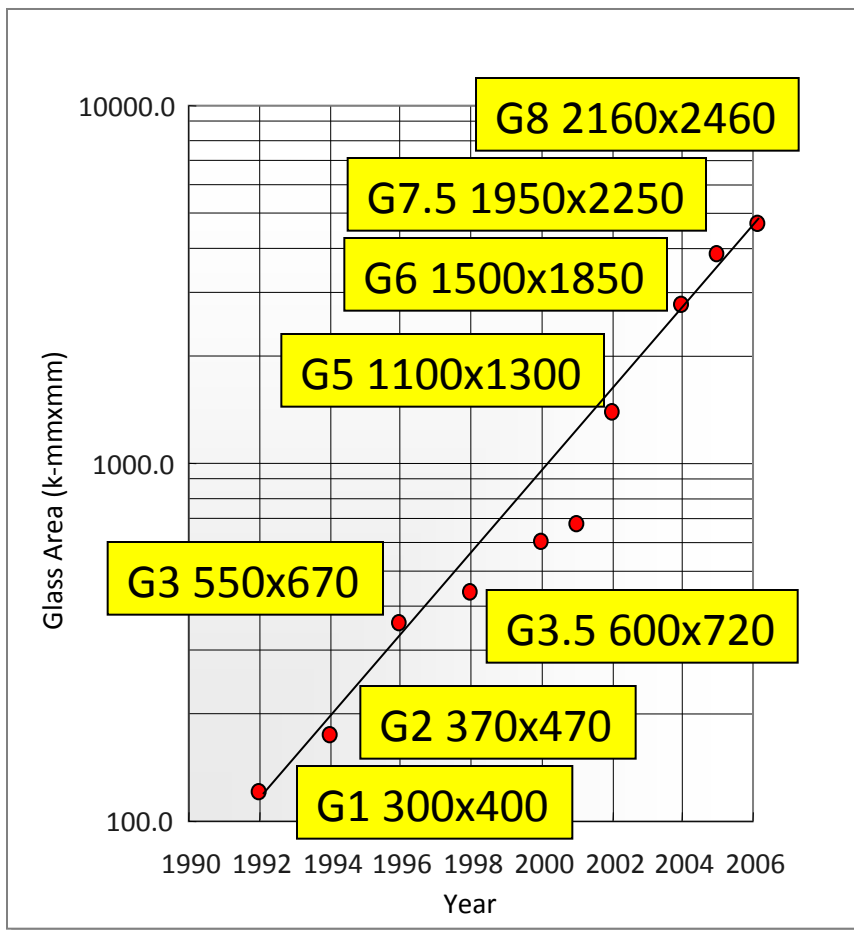
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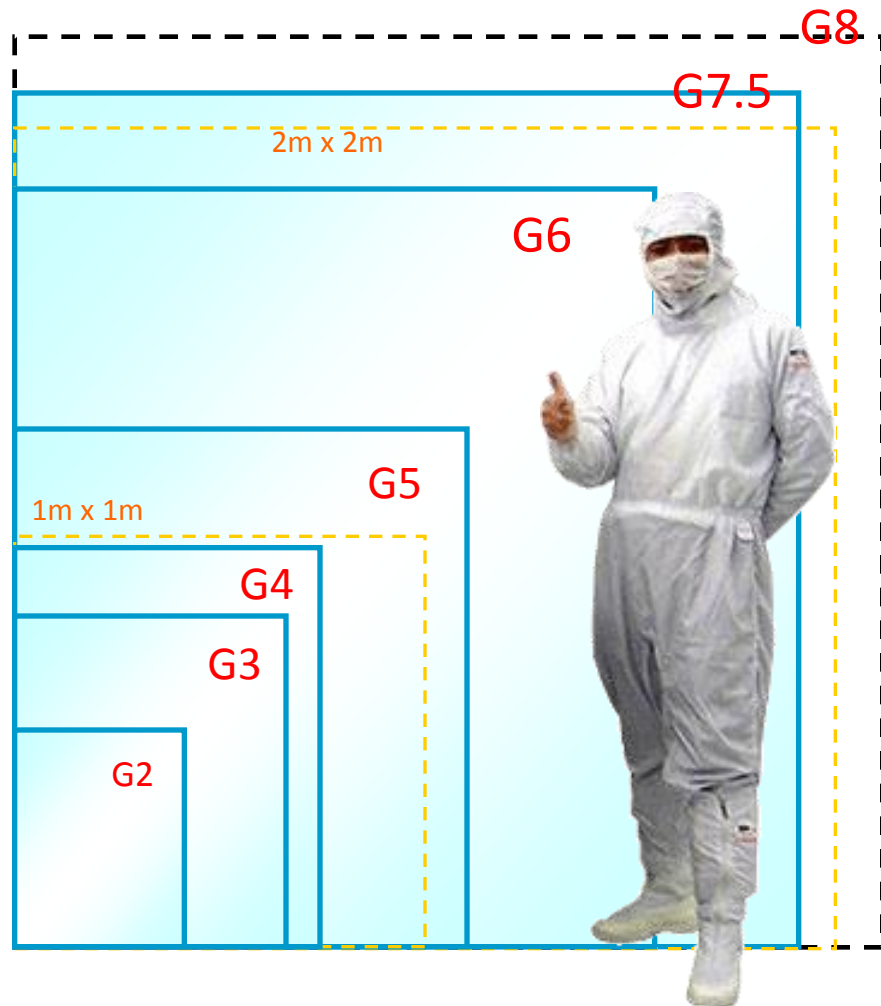
# Generation Migration in TFT-LCD

Mother Glass size grew 1.5 times every 1.5 years

## TFT LCD Generation Migration



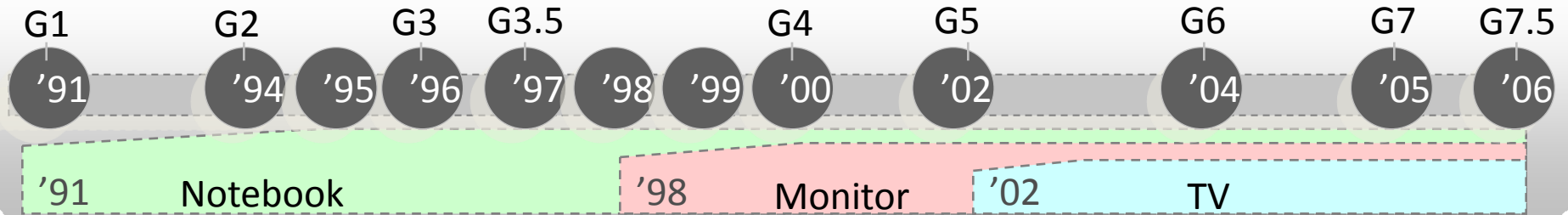
## Relative Glass Size in Each Generation



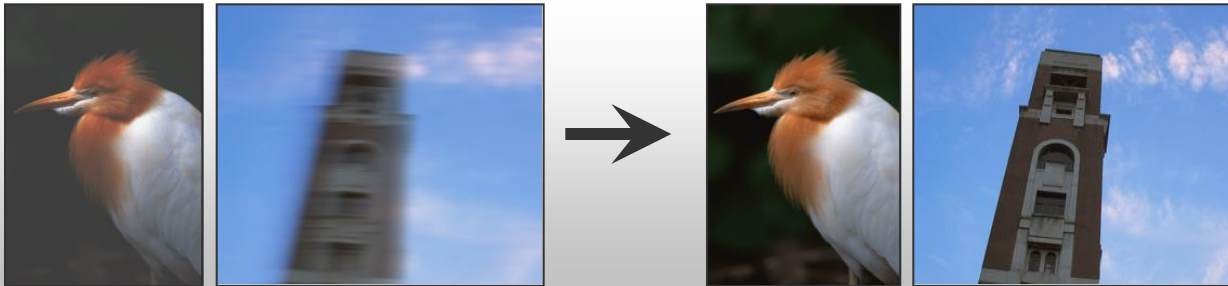


# Revolution Waves of TFT LCD

1st Wave: Product Introduction – Make The World Flat!



2nd Wave: Performance Enrichment – Make The World Gorgeous!

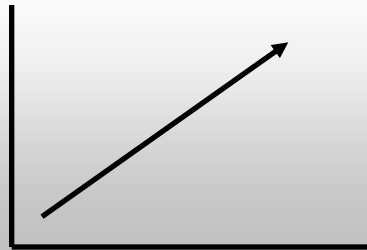


3rd Wave: Power & Material Efficiency – Make The World Green!

Power Utilization

10%

1%



Material Utilization



4th Wave: Functions for Human Interface – Make The World No Gap!

# Importance of High Contrast Ratio



**Contrast Ratio Improvement can increase dark color performance.**

# Advanced MVA-mobile Technology



## Features

- Wide Viewing Angle (160° / 160°)
- Low Color Washout
- High Contrast Ratio (2100:1)

## Product Applications

- Mobile Phone
- DSC
- Mobile TV

AMVA-mobile

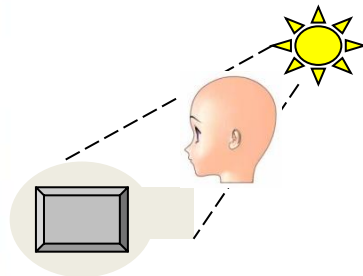


Conventional



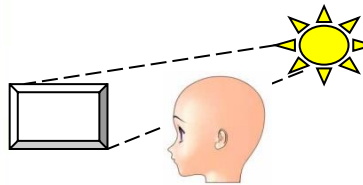
# Sunlight Readable Display

ATR-MVA



Under shadow  
30000 Lux

TMR+TN/WV



Direct sunlight  
80000 Lux



# Advanced Simulated Pulsed Driving



## Features

Fast response time to reduce motion blur  
(4ms Grey to Grey / 8ms MPRT)

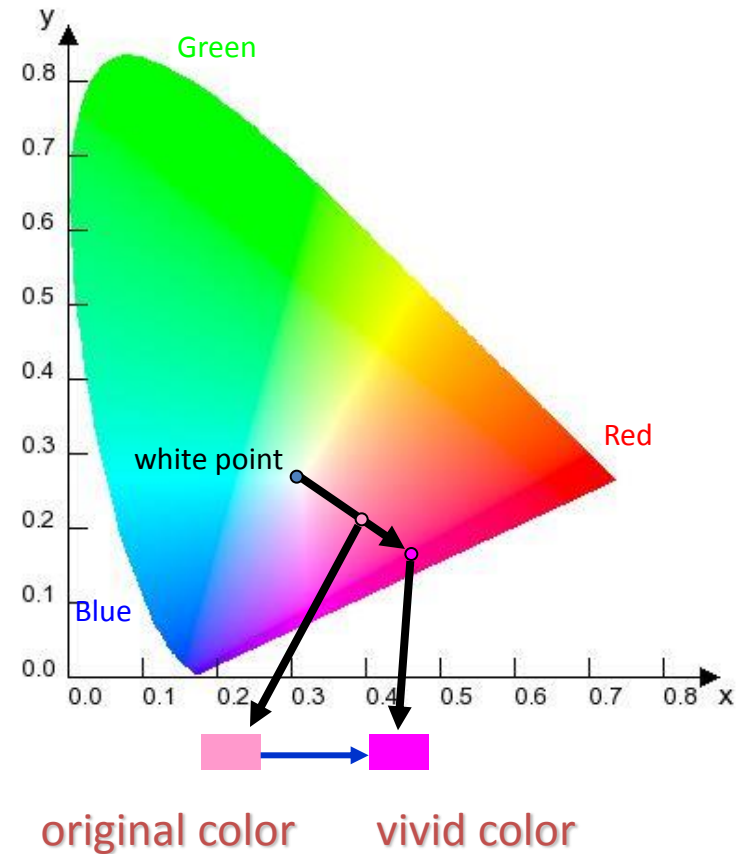
ASPD-mobile

Conventional



# Image Processing for Vivid Picture

## ✓ Saturation Enhancement

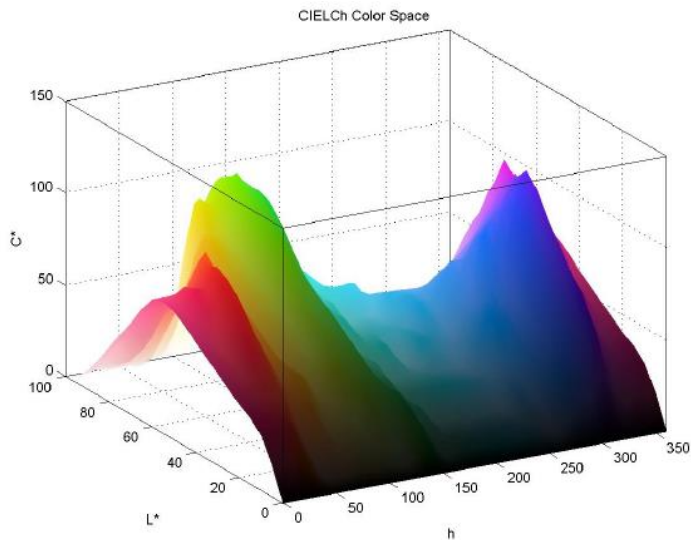




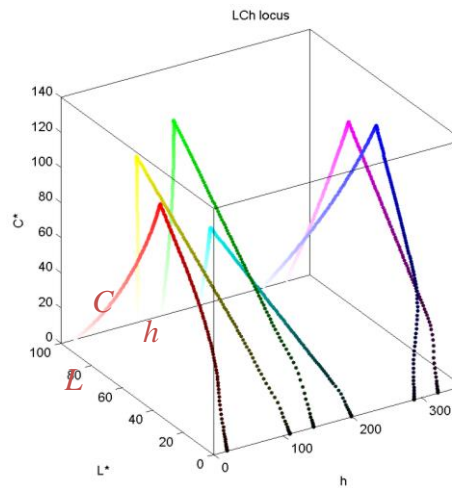
# Image Gamut Extension

- **Hue Division**
  - Outline panel's color characteristics
  - Find image gamut boundaries
  - Choose certain hue pages to decide image color templates

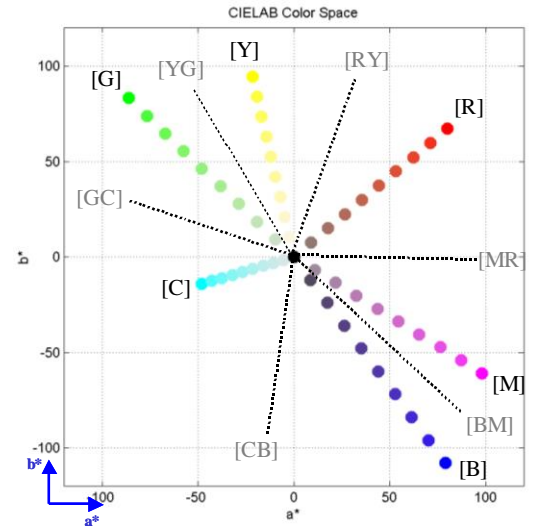
*Display's Color Gamut*



*Hue Pages*

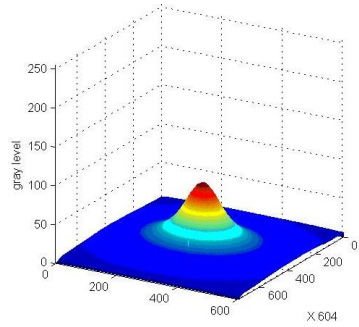


*Hue Division*

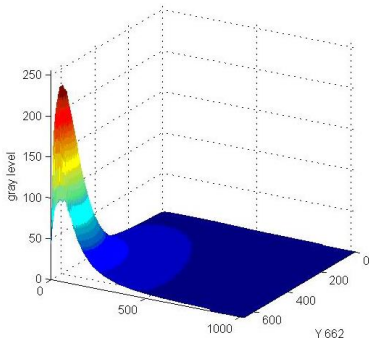
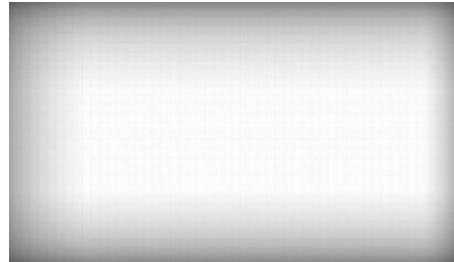


# High Dynamic Contrast

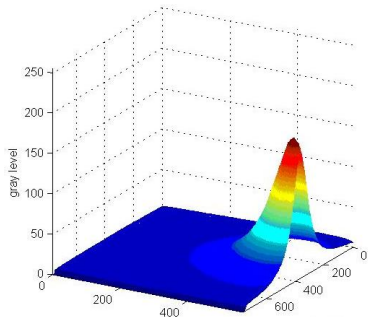
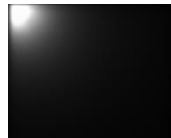
## Convolution Process



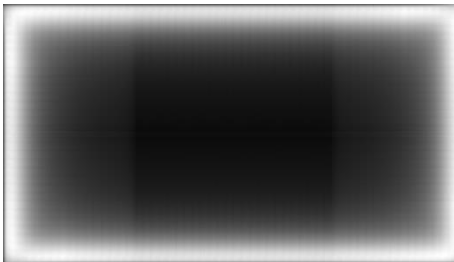
PSF - Center



PSF - Corner



PSF - Side



Measure PSF  
(Point Spread Function)



Calculate LED and LCD  
Control Signals.

# High Dynamic Contrast



Current = 9.5 A

Voltage = 10.95 V

Power Saving = 58% =  $1 - (9.5 \times 10.95) / 245.28$

\* LED B/L Full ON =  $22.4\text{A} \times 10.95\text{V} = 245.28\text{ W}$

$L_{\text{max}} = 418\text{ cd/m}^2$

$L_{\text{min}} = 0.04\text{ cd/m}^2$

$\text{CR} = 418 / 0.04 = 10,450$

# CABC Function

## •Purpose

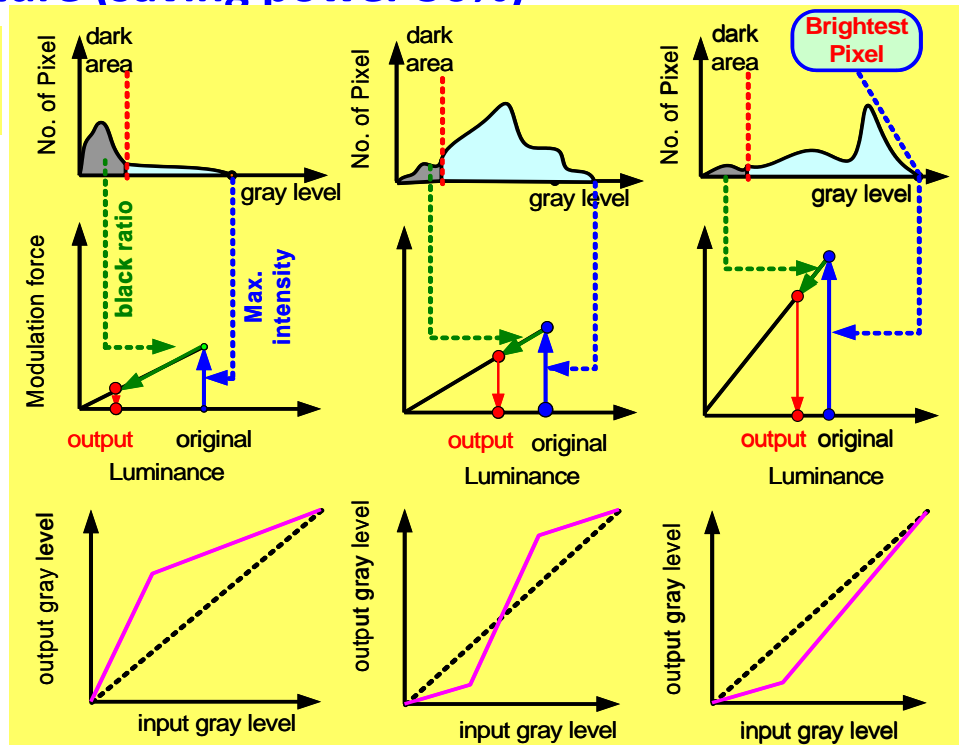
- To detect the image content and keep the same image quality with dimming.
- To reduce power consumption 50% in darker image.

## □ CABC Structure (saving power 50%)

Image information

Back light Gain

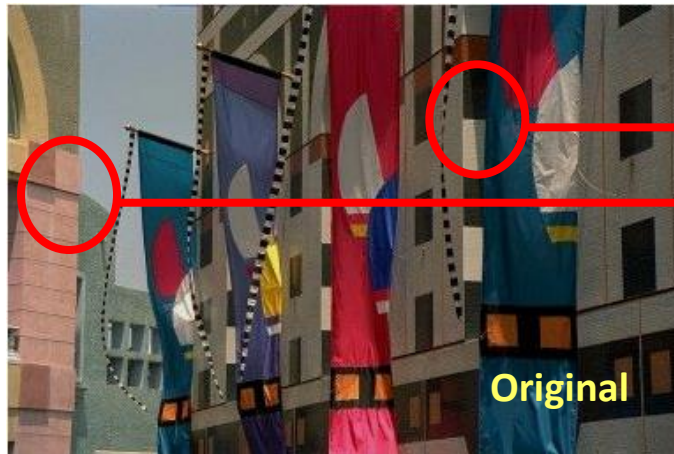
Gamma curve



Technology	'07 H1	'07 H2	'08	Remark
CABC	'07 1Q	Integrated IC cut1 '07 3Q	'07 4Q	C.i.1
		CABC FPGA Proto type	MP	

# Dynamic Backlight + Dynamic Contrast + Dynamic Gamma

- Improve contrast and detail
- Lower Power consumption



Contrast Ratio: 300

Contrast Ratio: 700  
Power saving 50%

C.i.1



# Slim & Light

## 0.9mm slim boarder (2.2")



### Features

- Possesses the slim boarder of 0.9mm on both the right and left sides
- The upper side boarder width of merely 1.2mm
- Be able to increase the active area and enhance the image sleekness

## 0.69mm mobile module (1.9")



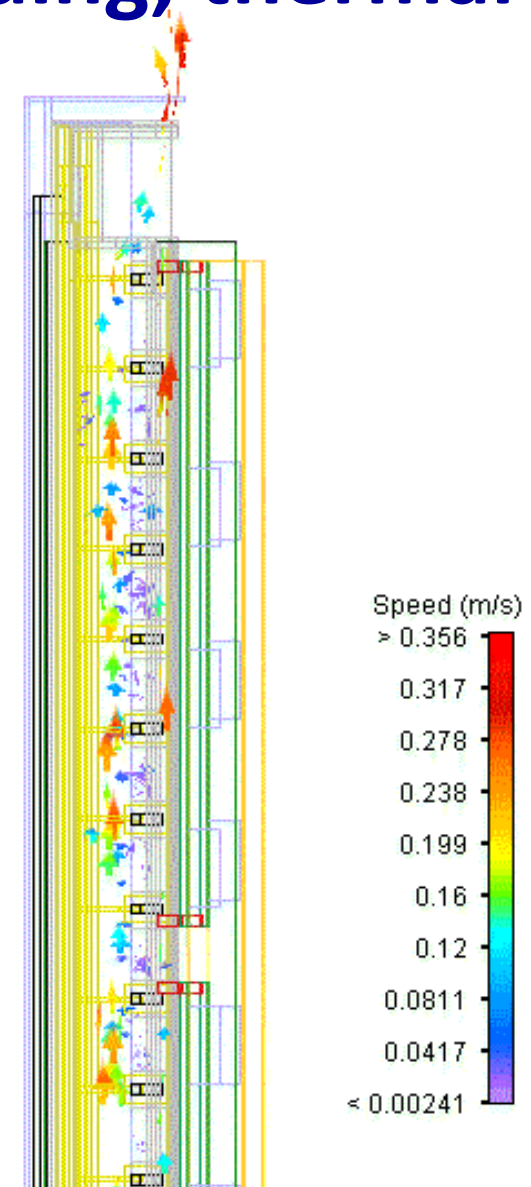
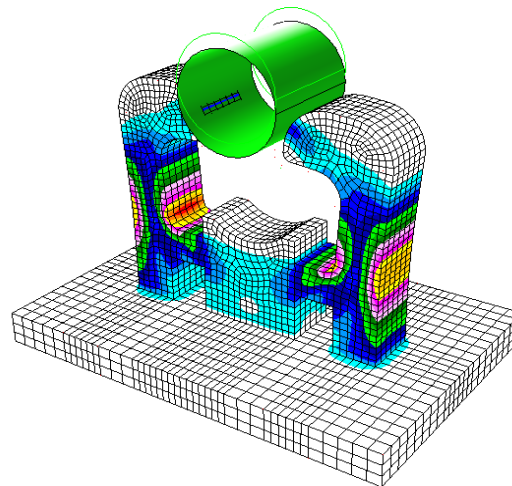
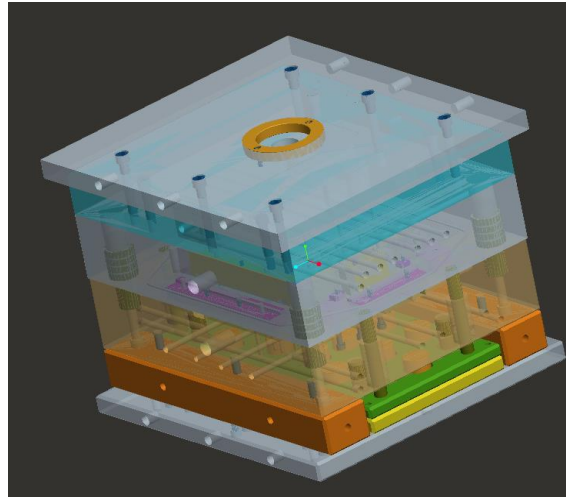
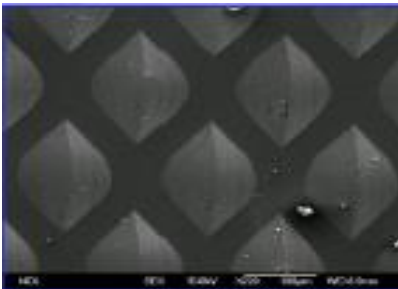
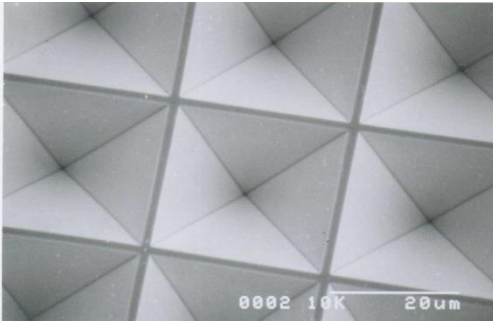
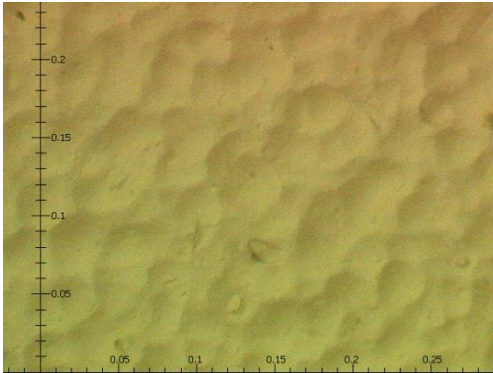
### Features

- Implement the latest glass thinning technology and shrink the thickness of related components
- 13% thinner than the thickness of a credit card
- Weight of 2.2 grams
- 400-nit high brightness
- Accomplish a multitude of features - light, slim, elegant and bright



# Precision Machinery Technology

## -- integrated micro-optics, molding, thermal



# Roll-to-Roll 3 $\mu$ m Direct Printing Patterning Technology Revolution

## Now

7-step process >>>  
film deposition >>>  
photo resist coating >>>  
resist baking >>>  
photo exposure >>>  
resist development >>>  
film etching >>>  
resist stripping >>>

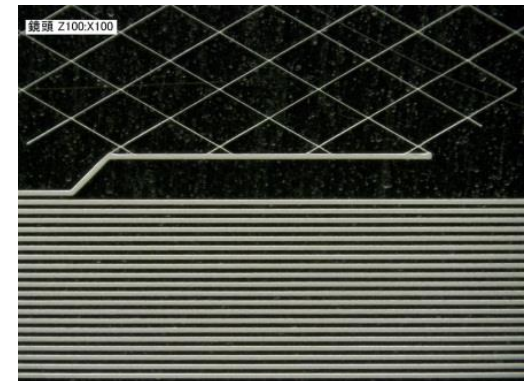
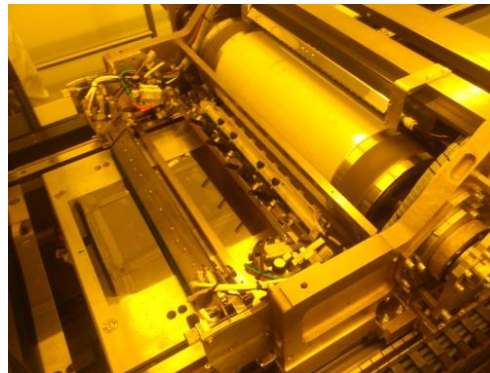
## Future

1-step  
fine-line direct printing



- Replace **7** process equipment with **1**
- Increase material usage from **5%** to **95%**

- Industry status: **sheet** process, **> 30 $\mu$ m**
- Komori-ITRI: **roll-to-roll** process, **3 $\mu$ m**



3 $\mu$ m

30 $\mu$ m

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# OLED Lighting Features

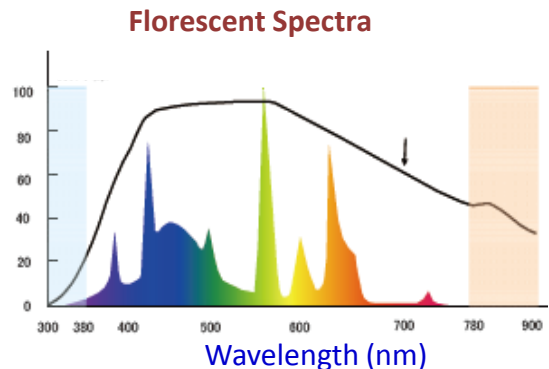
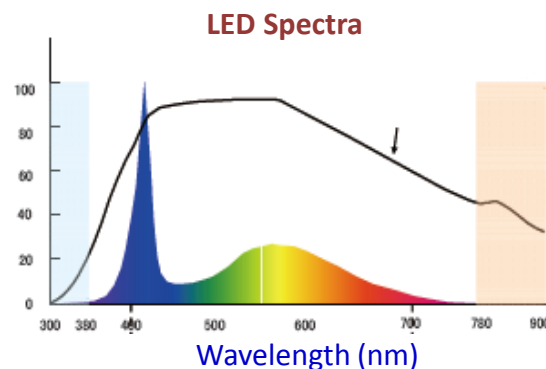
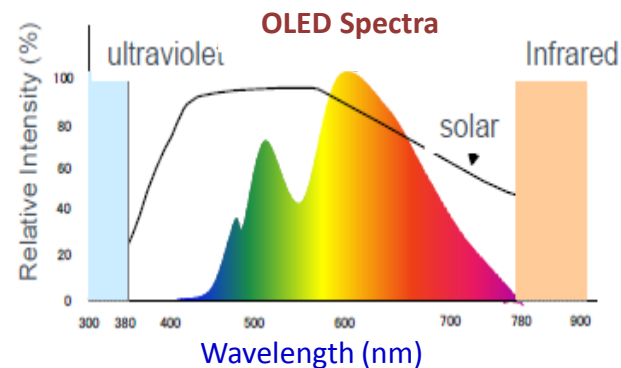
- **Simple:** surface light source
- **Innovative:** thin and light
- **Harmless:** UV-less, IR-less, Hg-free
- **Truthful:** closest to natural light
- **Beautiful:** high color rendering
- **Comfortable:** diffusive, non-glare
- **Power & material saving**



**Bendable**

**Very Thin** 0.3 mm thick

**Very Light** 0.05 g/cm<sup>2</sup>





customized



transparent



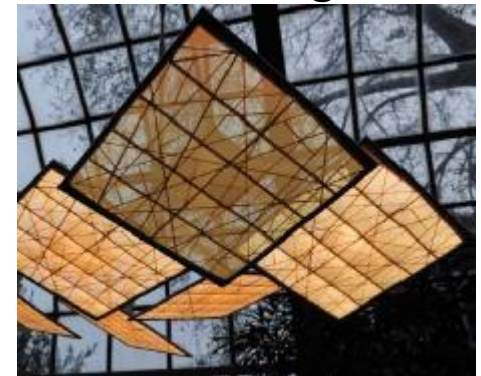
flexible



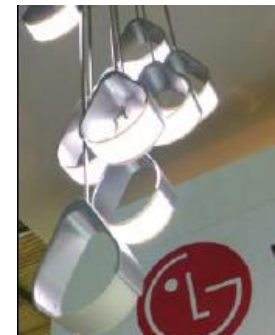
Interior designs



See through it



luminaire designs



## Audi



## OLED desk lamps



O'Leaf Luminaire  
Source: Philips



Wall Blade from Astron Fiamm



Victory – Brand Linterny  
Source: Novaled



Vanity from Lumiotec



Folz  
Source: Astron Fiamm



Olé  
Source: Astron Fiamm

## flexible OLED lighting



## large area and transparent



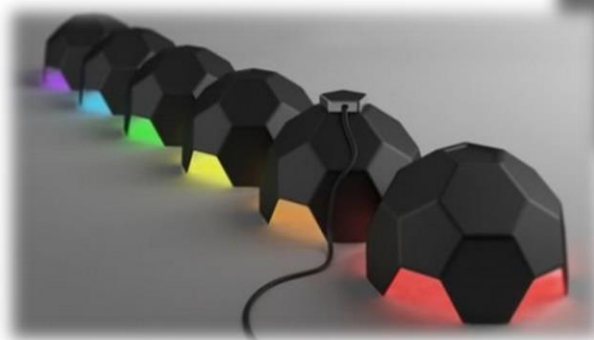
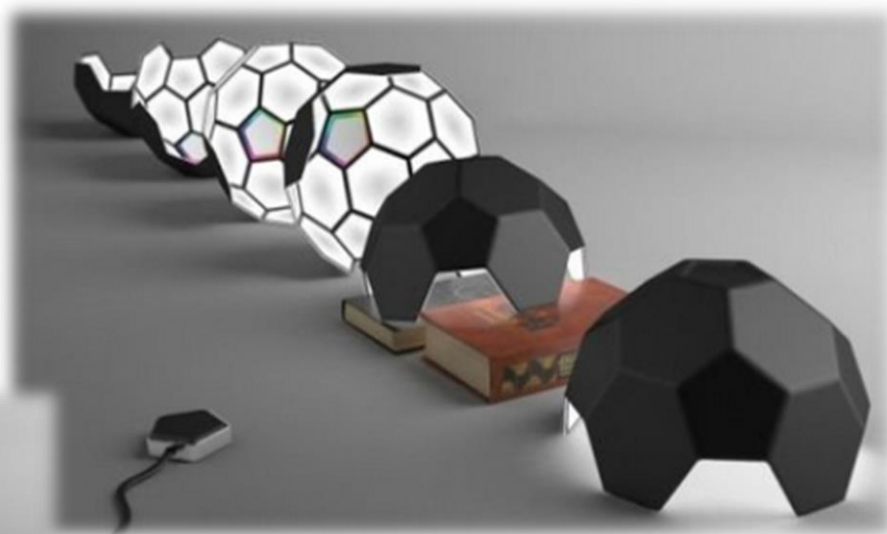
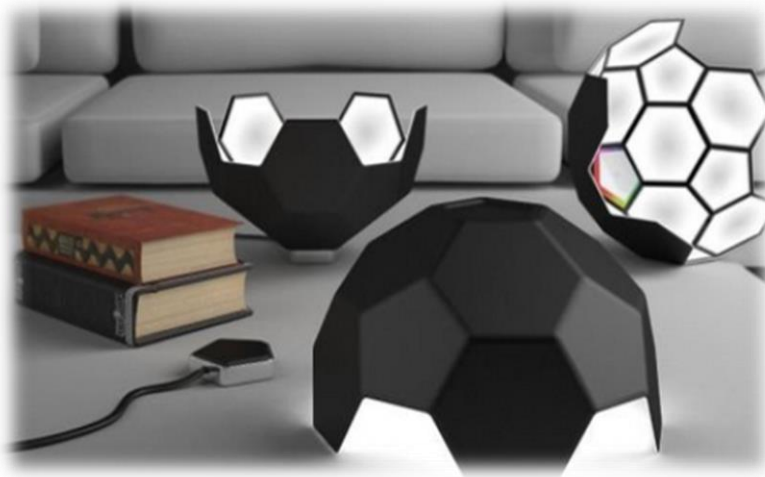
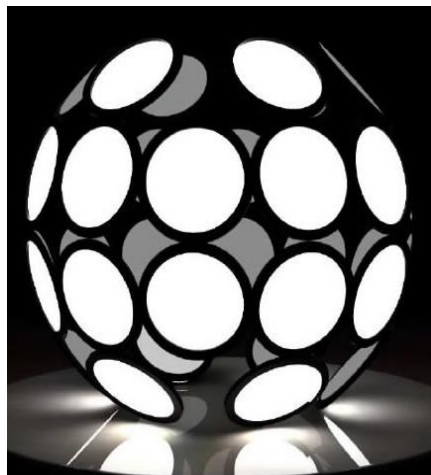




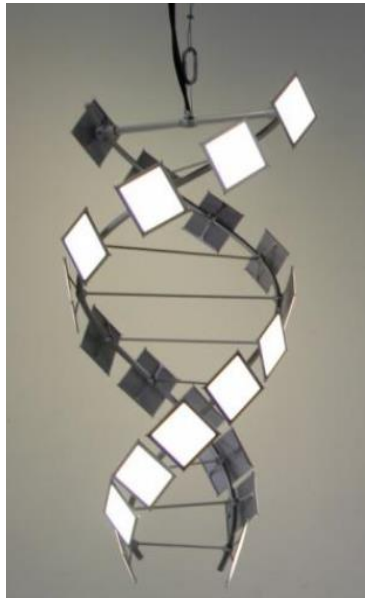
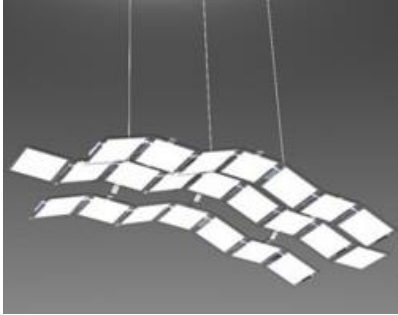
curved



3D



lamps



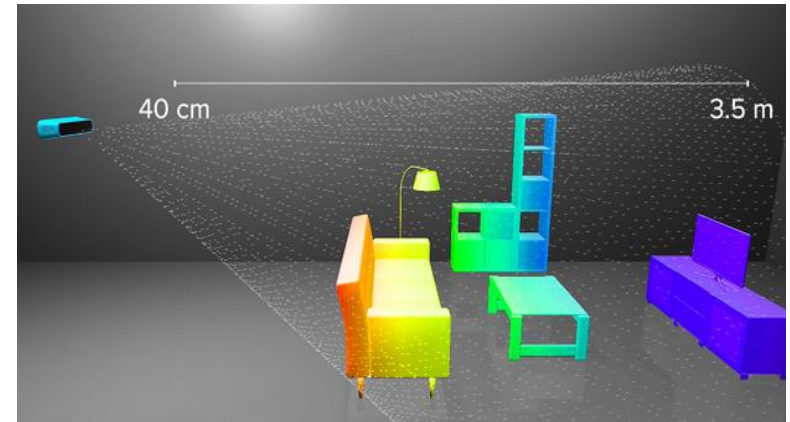
# Contents:

- 1. From Black-Body Radiation to Transistors**
- 2. Semiconductor Technologies**
- 3. Display Technologies**
- 4. Lighting Technologies**
- 5. 3D Image Systems**
- 6. Conclusion**



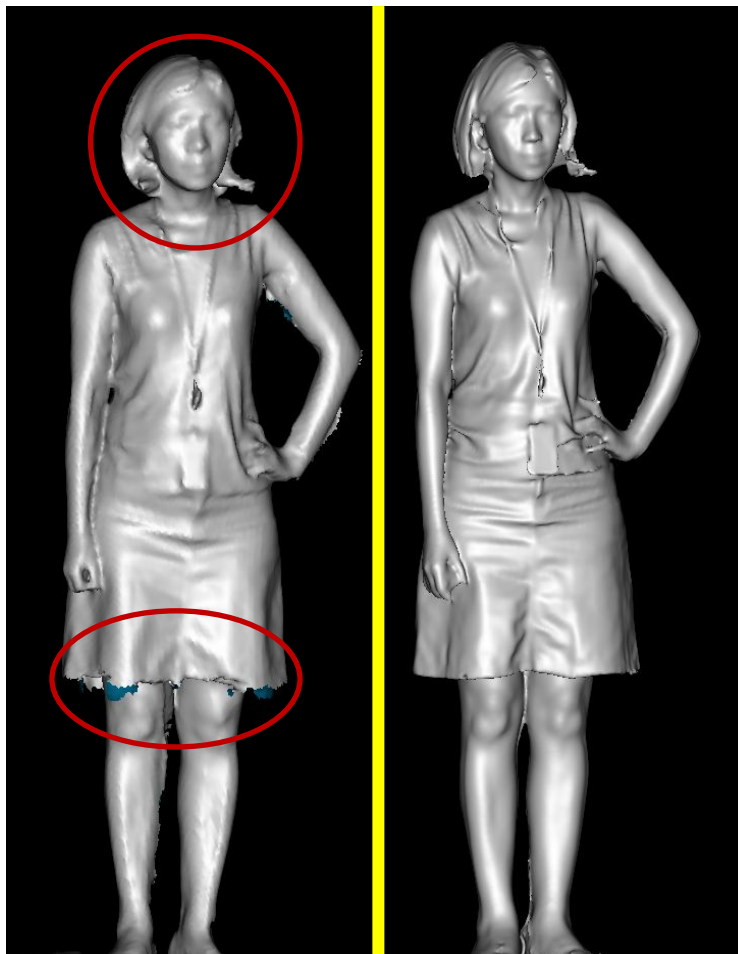
# Object Reconstruction – Handheld 3D Scanner

Capture the World in 3D



# Comparisons of 3D Scanners

	3D Systems Sense
Resolution	1 mm
Accuracy	0.9 mm
Measurement Rate	< 5 fps
Working Distance	35 ~300cm
Scan Area	57.5度
Weight	0.38 kg
Color	Yes
Light Source	IR Laser
Price	US 419



電光所 (Target)	
0.5~1 mm	Resolution
0.1mm	Accuracy
10 fps	Measurement Rate
35 ~ 65cm	Working Distance
45度	Scan Area
< 1.3kg	Weight
Yes	Color
IR LED	Light Source
	Price





# Indoor Space Reconstruction - Google

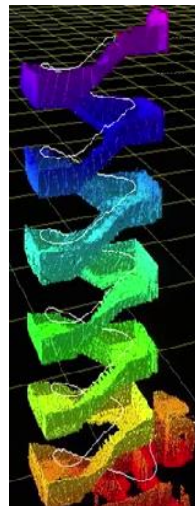
Tango project:  
stereo camera combined with tablets and smartphones



## Room reconstruction

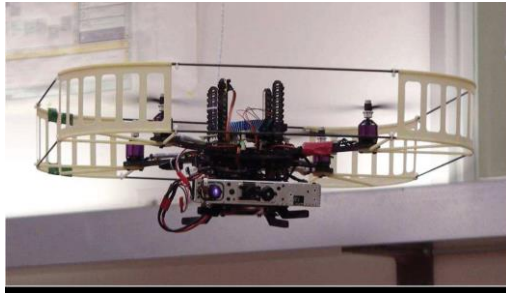


## Staircase reconstruction



# From On-Site Control to Cloud Control

- Stage 1: On-Site Control



on-board with Intel 4-Core i7-3612QE, 2.1 GHz  
➔ image process 、SLAM 、autopilot

Flight path control

- Stage 2: Cloud Control

autopilot



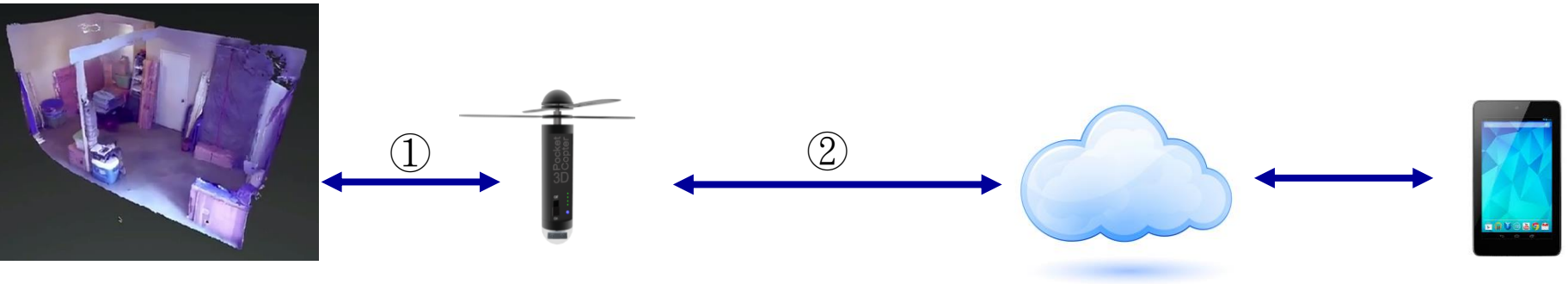
image process 、SLAM  
Flight path setting



Rendering  
Flight path control

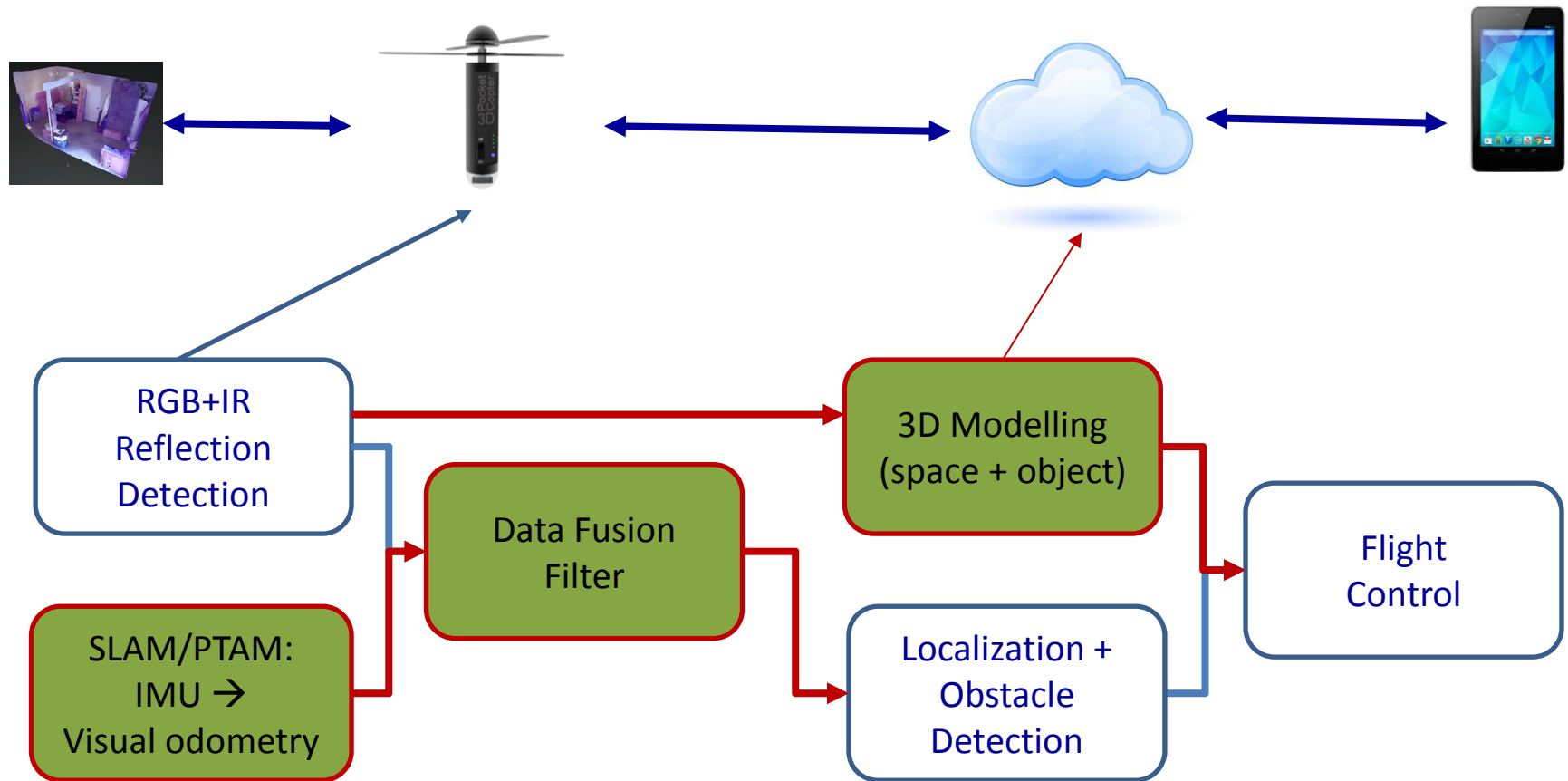


# System Operation - Initialization



- Detect environment complexity
- Initialize position
- Assign flight path patterns (eq., 之) from learning database

# System Operation - Scanning



➔ 3D modeling in cloud, real-time adjusting flight path (replace loop closure functions)

# Hardware: MAV



- Ascending Technologies (Germany), NTD 50k: on-board with Intel 4-Core i7-3612QE, 2.1 GHz for autopilot

- Parrot AR. Drone 2.0 (France), NTD 15k: iPod and android have App for easy controls



- 雷虎科技 (TW) : carrying capacity 200g

- GETOP (TW) : carrying capacity 4.5kg  
including camera



MAV: micro air vehicle or micro aerial vehicle

# Summary

- 1. It is a very exciting journey to do research.**
- 2. From black-body radiation (1901) to next-generation electronics (2020-2050), we continue to explore amazing sciences and technologies.**
- 3. Many frontier technologies will be in production 20 years from now and change our thinking completely.**